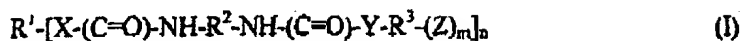


Serial No. 09/868,566

Art Unit: 1712



in which

 $m = 1$ or 2 , $n = 2$ or 3 ,

R^1 is a residue of a polyalkylene glycol after removal of the functional groups (hydroxyl or amino groups),

R^2 $[[=]]$ is C_{3-14} alkyl, aryl, aralkyl (residue of a diisocyanate after removal of the isocyanate groups),

X, Y $[[=]]$ is $-O-$, $-S-$ or $-NR^4$, where $R^4 = H$ or C_{1-4} alkyl or phenyl,

R^3 is a carbocyclic-aromatic or araliphatic $m+1$ -functional residue with groups Z directly attached to the an aromatic ring and Z $[[=]]$ is $-OH$ or $-NHR^4$ (residue of a polyphenol or aminophenol after removal of the functional groups).

B1

7 ~~21~~. (Previously entered) The composition claimed in claim ~~18~~, wherein component B) is dissolved in a liquid polyepoxide.

8 ~~22~~. (Previously entered) The composition claimed in claim ~~18~~, wherein component B) is reacted with a stoichiometric excess of a polyepoxide.

9 ~~23~~. (Currently amended) The composition claimed in claim ~~18~~ further comprising wherein
D) comprises a latent hardener selected from the group consisting of dicyanodiamide, guanamines, guanidines, aminoguanidines, solid aromatic diamines and mixtures thereof and optionally a hardening accelerator; and

E) optionally plasticizers, reactive diluents, rheology aids, fillers, wetting agents, antiagers and stabilizers.

10 ~~24~~. (Previously added) A cured composition of claim ~~18~~ having an impact peel energy of at least 5 J at -20°C (to ISO 11343).

11 ~~25~~. (Previously added) The production of composite materials, potting compounds in the electrical and electronics industries and die-attach adhesive for the production of circuit boards in the electronics industry wherein the adhesive comprises the composition of claim ~~24~~. ¹⁰

~~26~~. (Cancelled)

27. (Currently amended) The method A-process for hardening a composition of claim ~~26~~ ¹⁵ which comprises heating the composition to a temperature of 80°C to 210°C .

28. (Currently amended) A process method for bonding members selected from the group